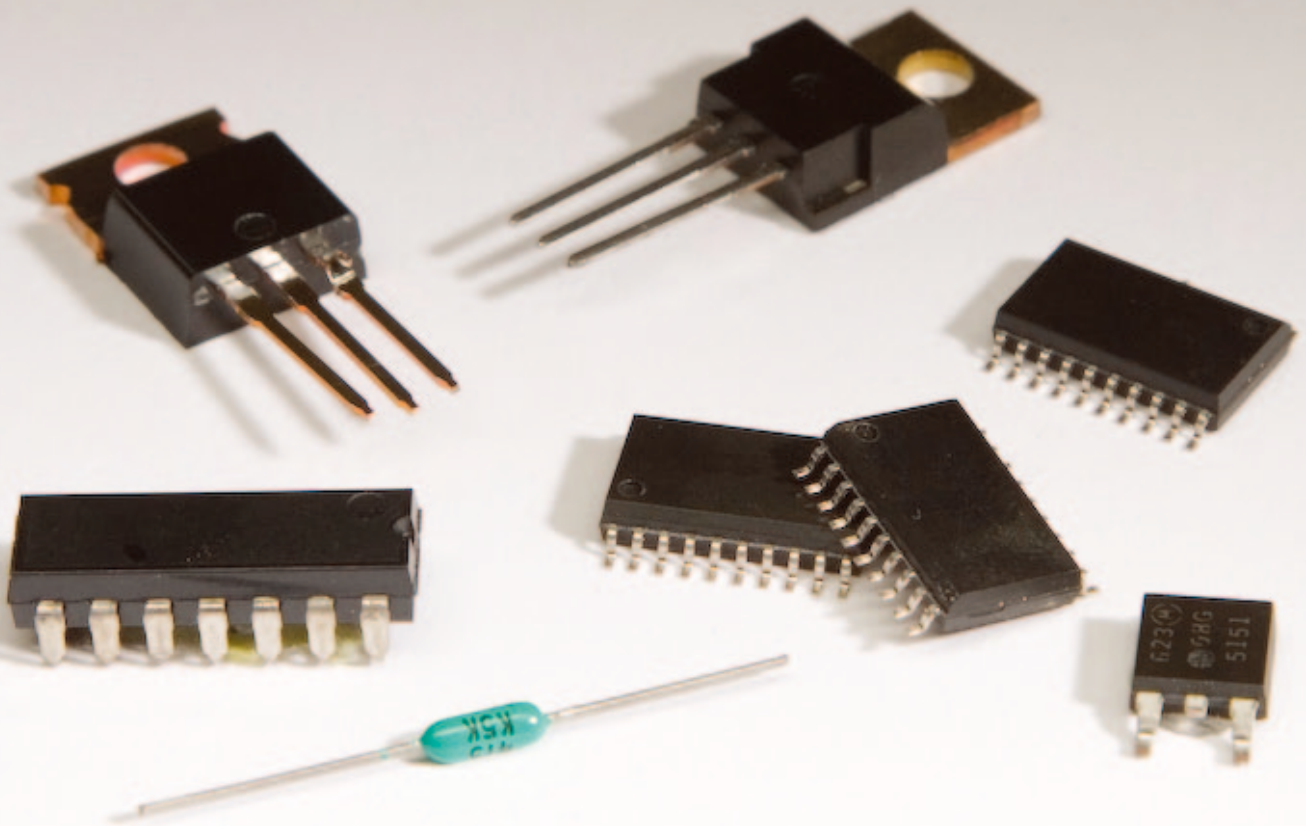


## Ablebond ABP-8000

Die Attach Adhesive



As higher-temperature processes are now the norm, semiconductor packaging materials must be able to withstand these stressful conditions while still maintaining their integrity and performance. To this end, Henkel has developed Ablebond ABP-8000 that addresses the needs of high-reliability, small die size and high power lead-frame applications. Ablebond ABP-8000 offers the high adhesion, excellent reliability, outstanding dispensing performance and the highest electrical and thermal conductivity in any organic based system.





# Ablebond ABP-8000

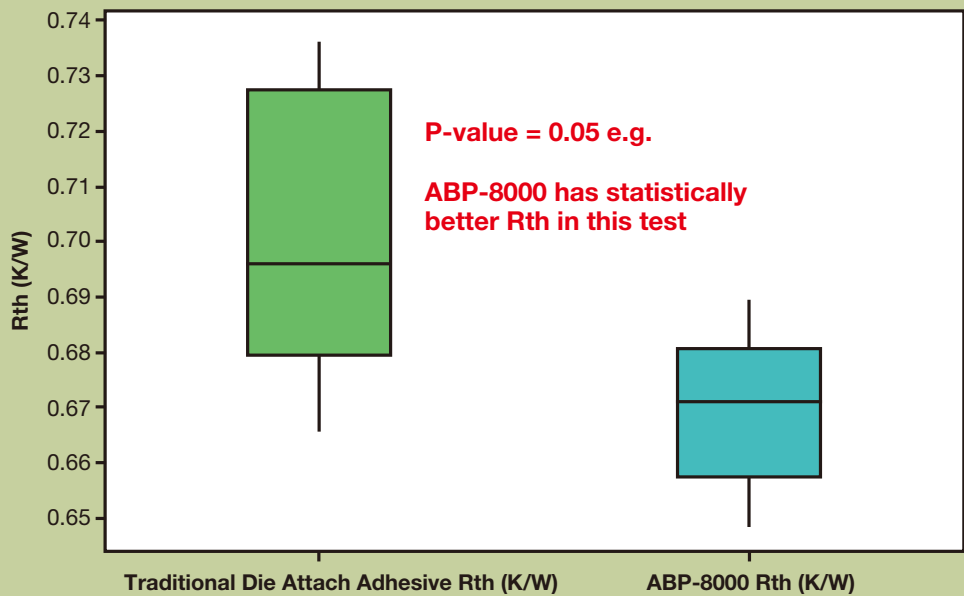


## Key Features

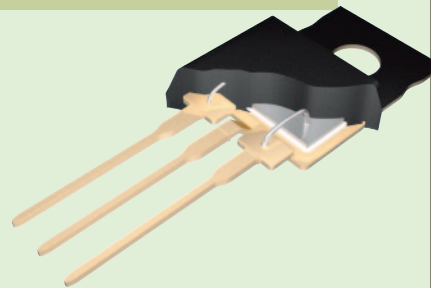
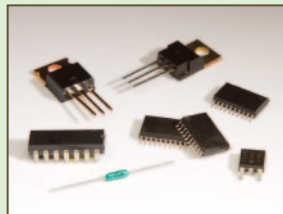
Open Time	No sensitivity Up to the 60 minutes interval
Stage Time	Robust Up to a minimum of 8 hours
Adhesion Performance	Good stable adhesion at a variety of different process intervals when using small to medium die sizes when the LDF is AgCu or PPF

## Thermal Resistance (Rth)

Thermal Resistance, Rth (K/W), Data for ABP-8000 versus traditional die attach adhesive



Test Assumption: Equivalent Bond Line Thickness



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